

● General Description

The AGM15P22AS combines advanced trench MOSFET technology with a low resistance package to provide extremely low $R_{DS(ON)}$

This device is ideal for load switch and battery protection applications.

● Features

- Advance high cell density Trench technology
- Low $R_{DS(ON)}$ to minimize conductive loss
- Low Gate Charge for fast switching
- Low Thermal resistance
- 100% Avalanche tested
- 100% DVDS tested

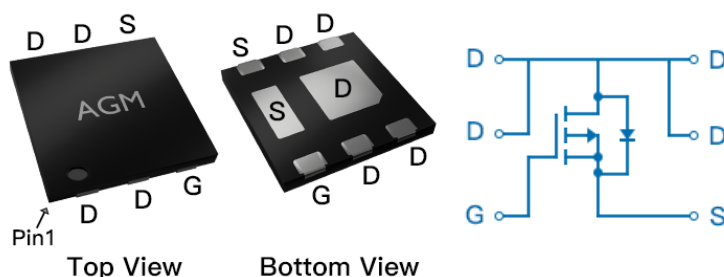
● Application

- MB/VGA Vcore
- SMPS 2nd Synchronous Rectifier
- POL application
- BLDC Motor driver

Product Summary

BVDSS	RDSON	ID
-16V	20mΩ	-9.0A

DFN2*2 Pin Configuration



Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
15P22	AGM15P22AS	DFN2*2	178mm	8mm	3000

Table 1. Absolute Maximum Ratings (TA=25°C)

Symbol	Parameter	Value	Unit
VDS	Drain-Source Voltage (VGS=0V)	-16	V
VGS	Gate-Source Voltage (VDS=0V)	±10	V
ID	Drain Current-Continuous(Tc=25°C) (Note 1)	-9.0	A
	Drain Current-Continuous(Tc=100°C)	-6.0	A
IDM (pluse)	Drain Current-Pulsed (Note 2)	-36	A
PD	Maximum Power Dissipation(Tc=25°C)	2.1	w
	Maximum Power Dissipation(Tc=100°C)	0.85	w
EAS	Avalanche energy (Note 3)	---	mJ
TJ,TSTG	Operating Junction and Storage Temperature Range	-55 To 150	°C

Table 2. Thermal Characteristic

Symbol	Parameter	Typ	Max	Unit
RθJA	Thermal Resistance Junction-ambient (Steady State) ¹	---	60	°C/W

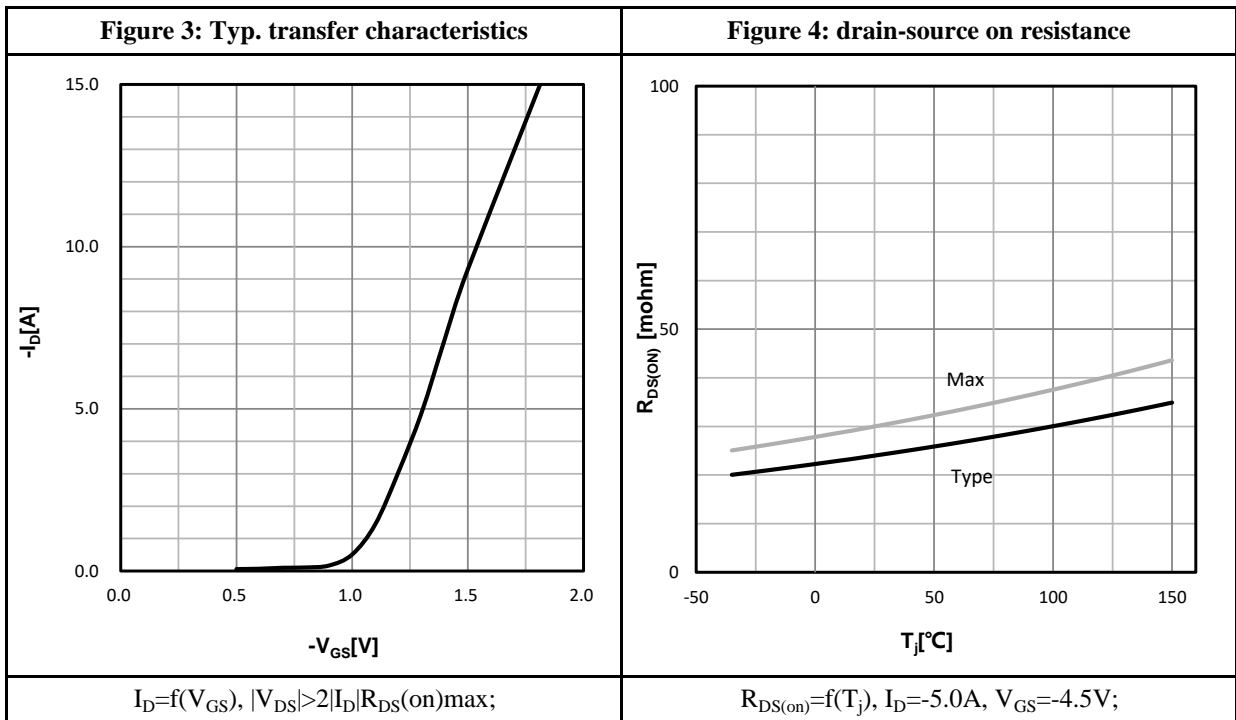
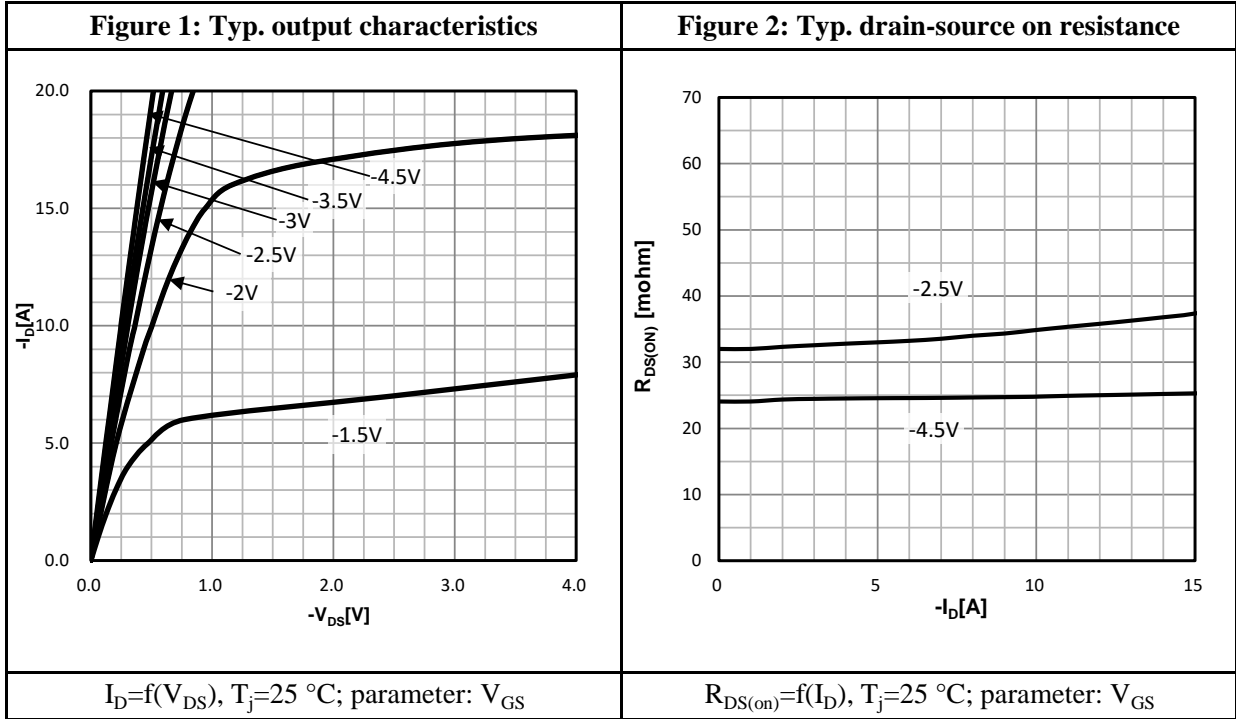
Table 3. Electrical Characteristics (T_J=25°C unless otherwise noted)

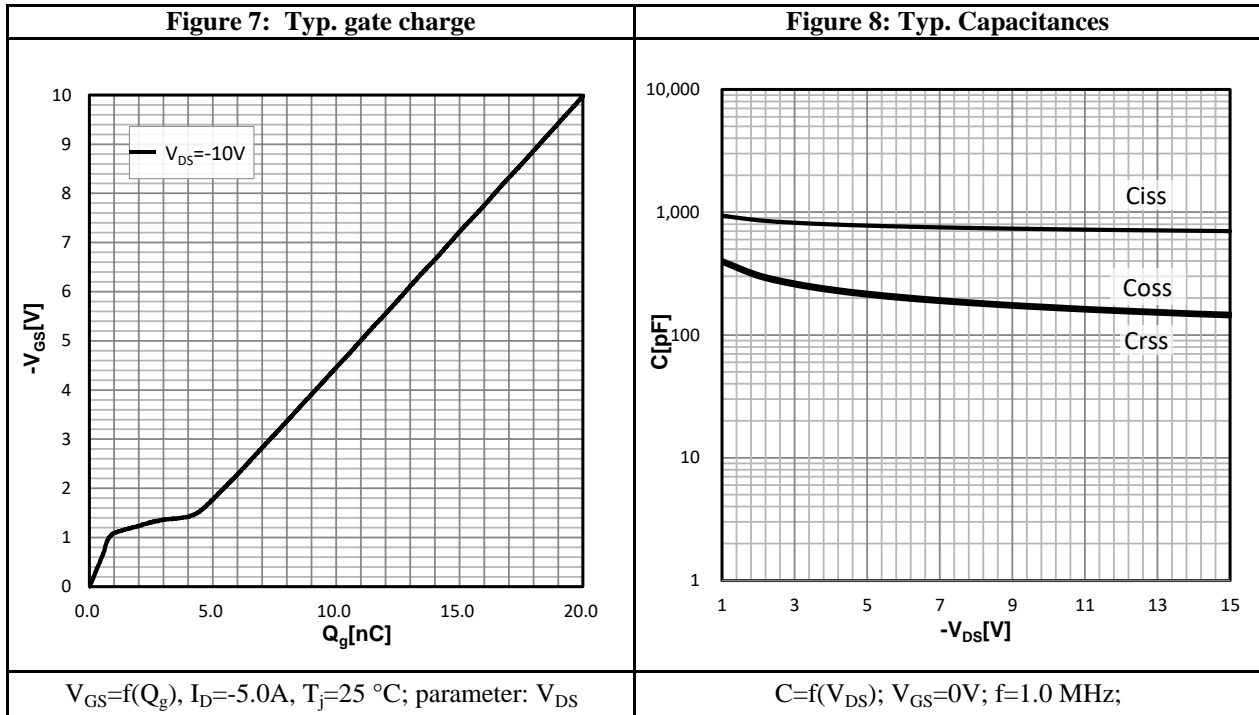
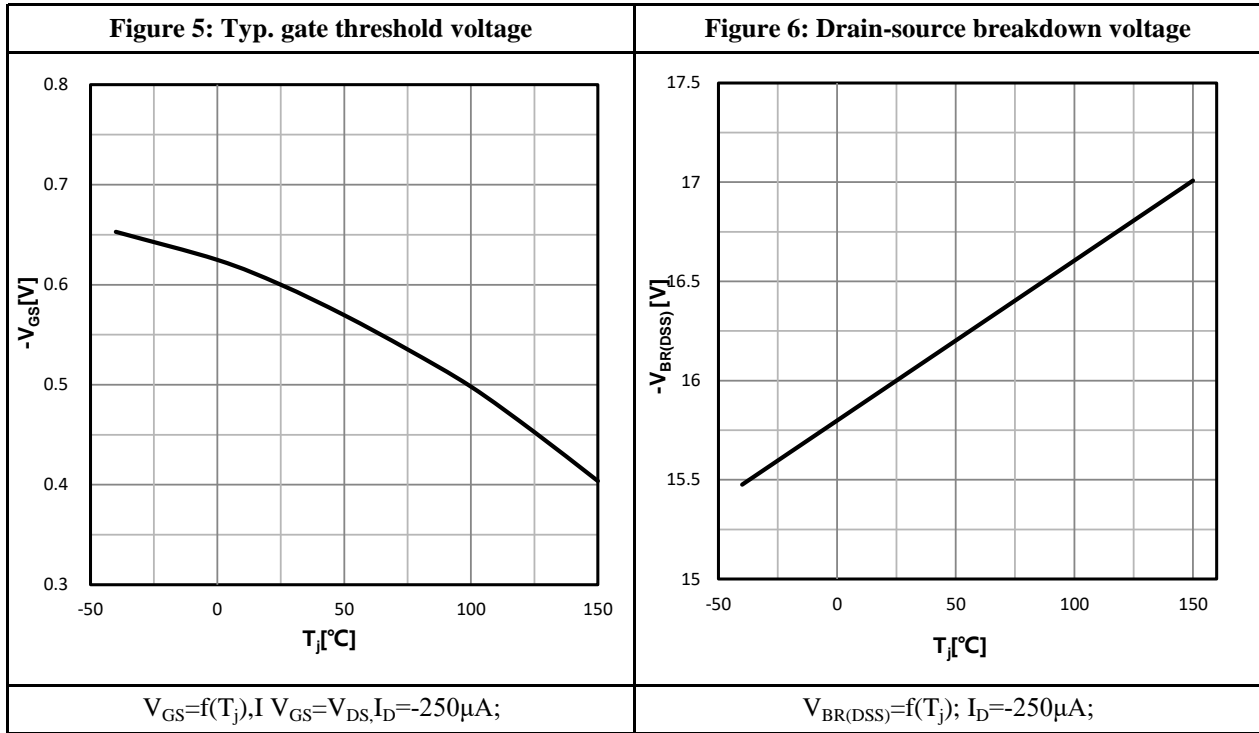
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
On/Off States						
BVDSS	Drain-Source Breakdown Voltage	VGS=0V ID=-250μA	-16	--	--	V
IDSS	Zero Gate Voltage Drain Current	VDS=-16V,VGS=0V	--	--	-1	μA
IGSS	Gate-Body Leakage Current	VGS=±10V,VDS=0V	--	--	±100	nA
VGS(th)	Gate Threshold Voltage	VDS=VGS,ID=-250μA	-0.4	-0.6	-1.0	V
gFS	Forward Transconductance	VDS=-5V,ID=-2A	--	5	--	S
RDS(on)	Drain-Source On-State Resistance	VGS=-4.5V, ID=-3A	--	20	27	mΩ
		VGS=-2.5V, ID=-2A	--	28	35	mΩ
Dynamic Characteristics						
Ciss	Input Capacitance	VDS=-10V,VGS=0V, F=1MHZ	--	728	--	pF
Coss	Output Capacitance		--	172	--	pF
Crss	Reverse Transfer Capacitance		--	164	--	pF
Rg	Gate resistance	VGS=0V, VDS=0V,f=1.0MHz	--	8	--	Ω
Switching Times						
td(on)	Turn-on Delay Time	ID =-5A VDS = -10V VGS =-4.5V RG = 8Ω	--	13	--	nS
tr	Turn-on Rise Time		--	36	--	nS
td(off)	Turn-Off Delay Time		--	32	--	nS
tf	Turn-Off Fall Time		--	12	--	nS
Qg	Total Gate Charge	VGS=-10V, VDS=-10V, ID=-5A	--	20	--	nC
Qgs	Gate-Source Charge		--	0.9	--	nC
Qgd	Gate-Drain Charge		--	3.2	--	nC
Source-Drain Diode Characteristics						
ISD	Source-Drain Current(Body Diode)		--	--	-9.0	A
VSD	Forward on Voltage	VGS=0V,IS=-3A	--	--	-1.2	V
trr	Reverse Recovery Time	Isd=-3A , dl/dt=100A/μs , TJ=25°C	--	--	--	ns
Qrr	Reverse Recovery Charge		--	--	--	nc

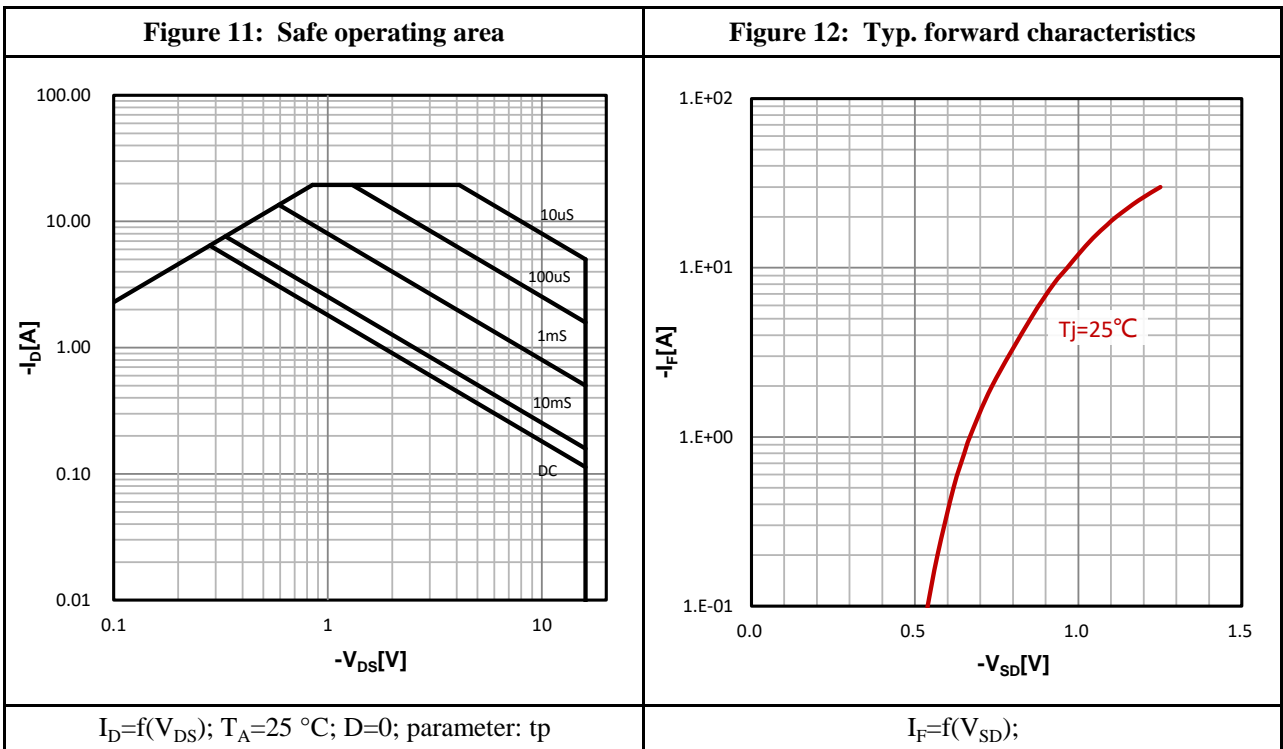
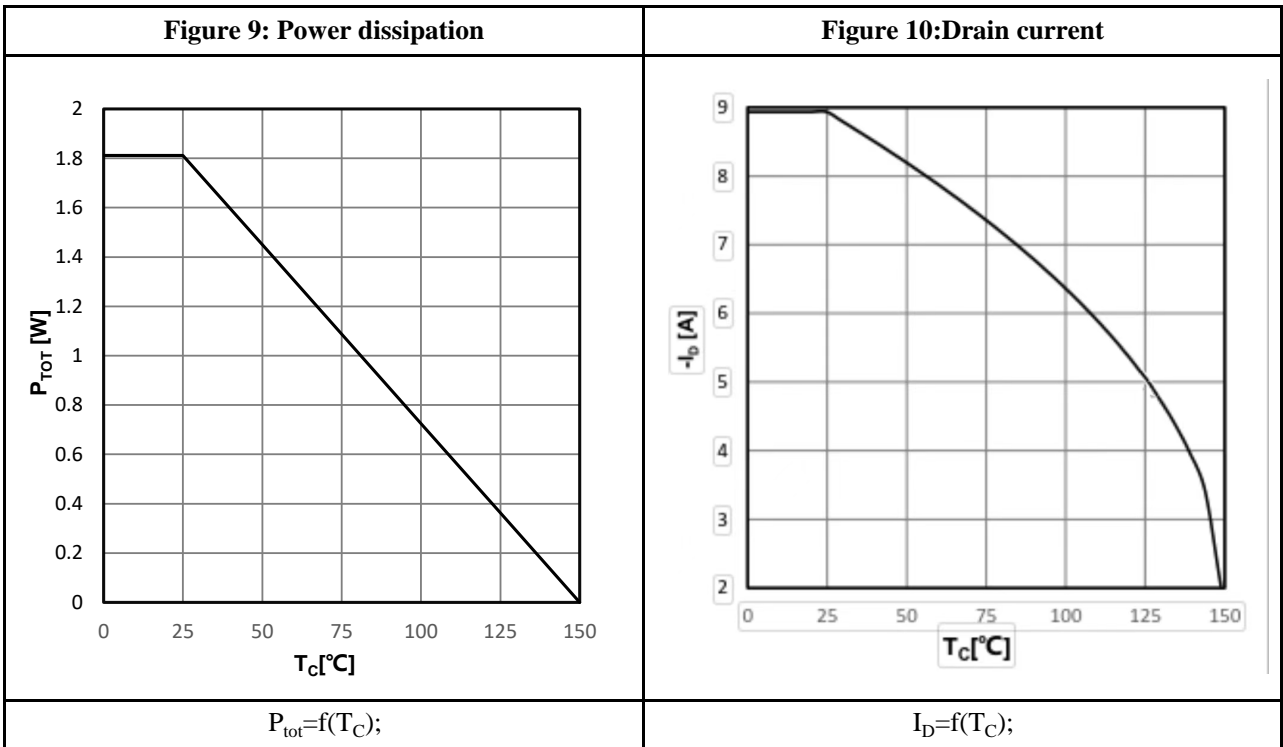
Notes 1.The maximum current rating is package limited.

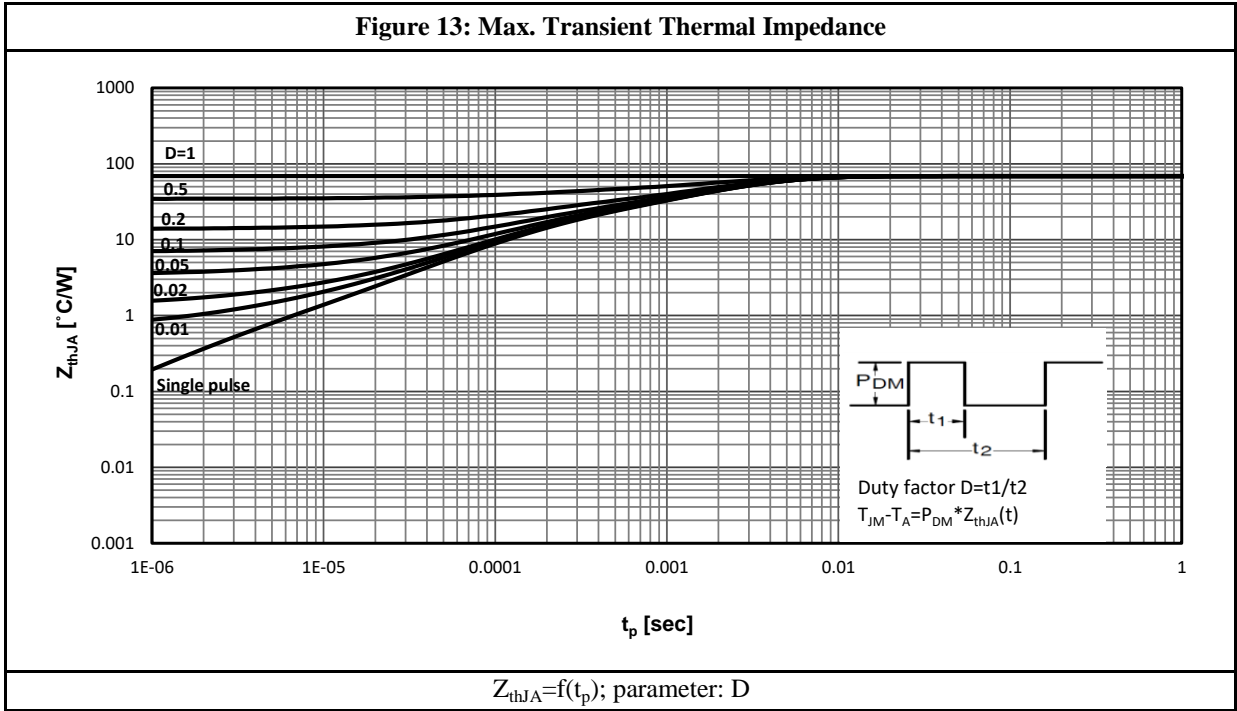
Notes 2.Repetitive Rating: Pulse width limited by maximum junction temperature

Notes 3.EAS condition: T_J=25°C

Characteristics Curve:








Test Circuit & Waveform:

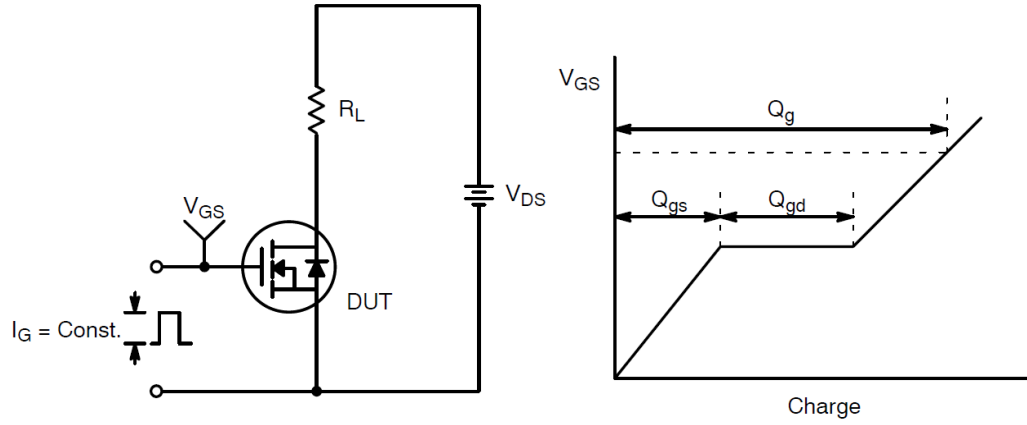


Figure 14: Gate Charge Test Circuit & Waveform

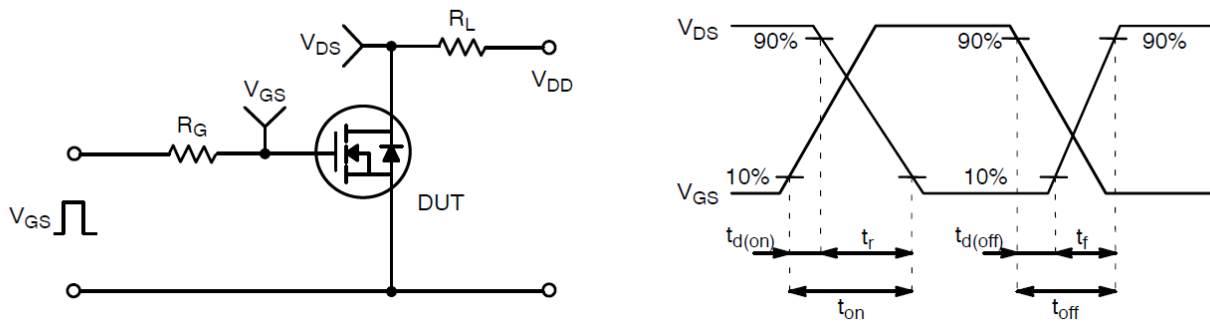


Figure 15: Resistive Switching Test Circuit & Waveforms

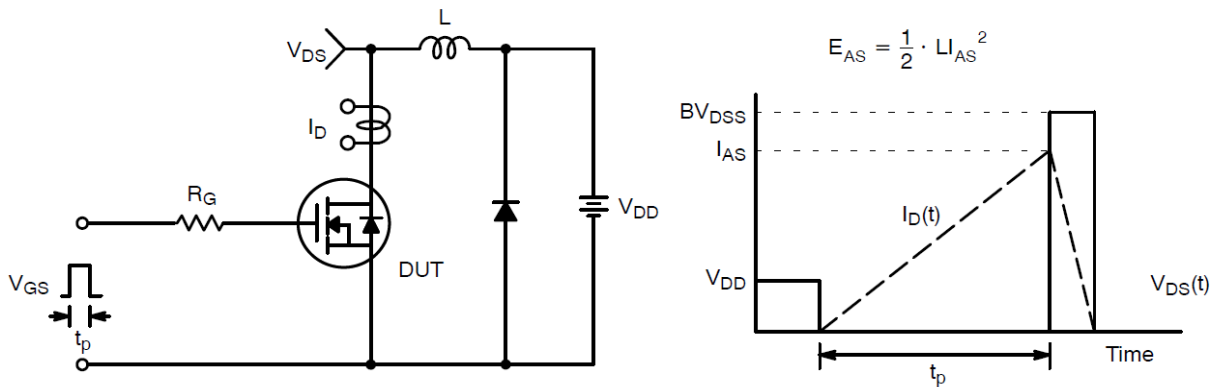
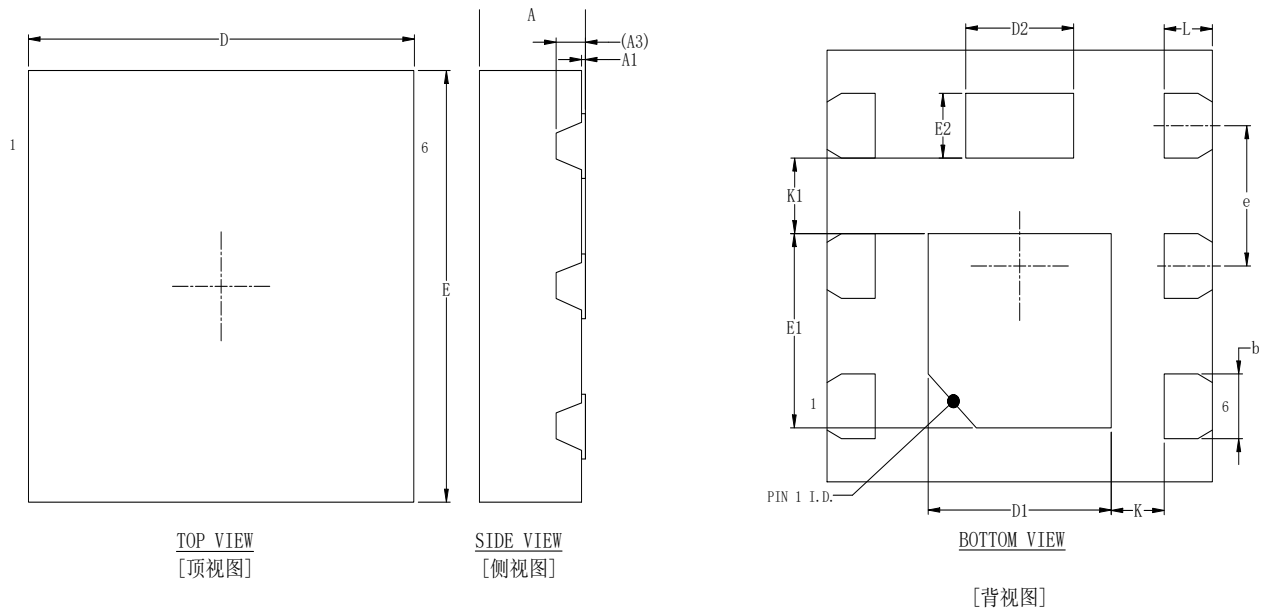
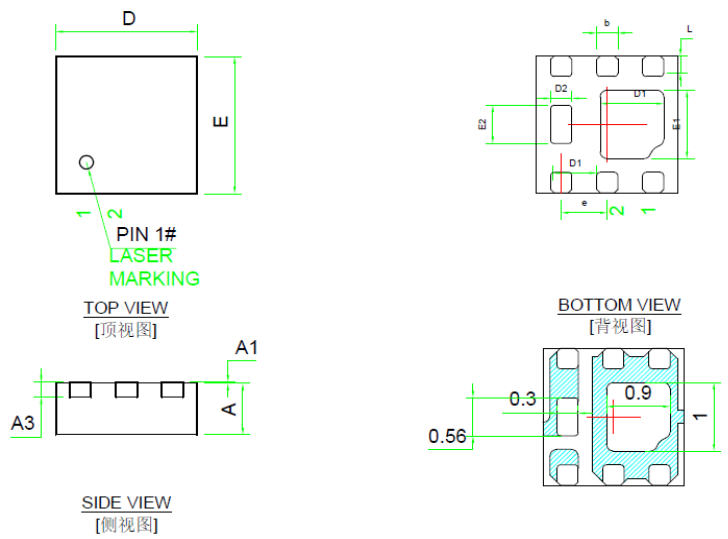


Figure 16: Unclamped Inductive Switching Test Circuit & Waveforms

•Dimensions (DFN2×2)


	SYMBOL	MIN	NOM	MAX	
TOTAL THICKNESS	A	0.5	0.55	0.6	
STAND OFF	A1	0	0.02	0.05	
L/F THICKNESS	A3	0.152 REF			
LEAD WIDTH	b	0.25	0.3	0.35	
BODY SIZE	X	D	1.9	2	2.1
	Y	E	1.9	2	2.1
LEAD PITCH	e	0.65 BSC			
EP SIZE	X	D1	0.85	0.95	1.05
		D2	0.46	0.56	0.66
	Y	E1	0.8	0.9	1
		E2	0.2	0.3	0.4
LEAD LENGTH	L	0.2	0.25	0.3	
LEAD TIP TO EP EDGE	K	0.275 REF			
EP EDGE TO EP EDGE	K1	0.35 REF			



Symbol	Dimensions In Millimeters		
	Min	Nom	Max
A	0.700	0.750	0.800
A1	0.000	0.020	0.050
A3	0.203REF		
b	0.250	0.300	0.350
D	1.900	2.000	2.100
D1	0.850	0.900	0.950
D2	0.250	0.300	0.350
e	0.650BSC		
E	1.900	2.000	2.100
E1	0.950	1.000	1.050
E2	0.510	0.560	0.610
L	0.250	0.300	0.350


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